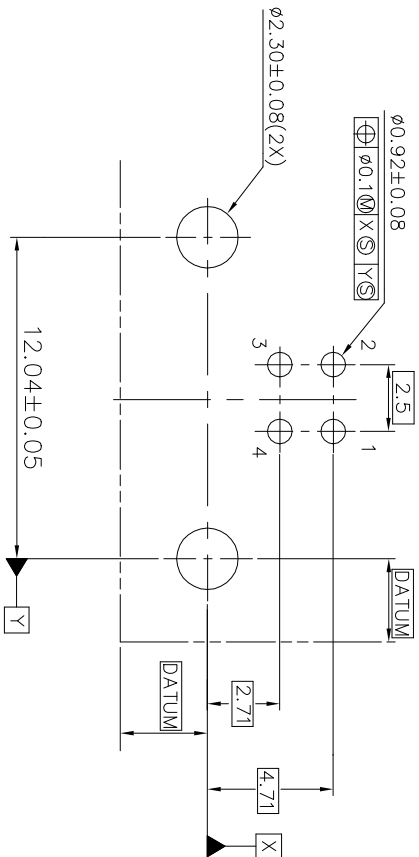
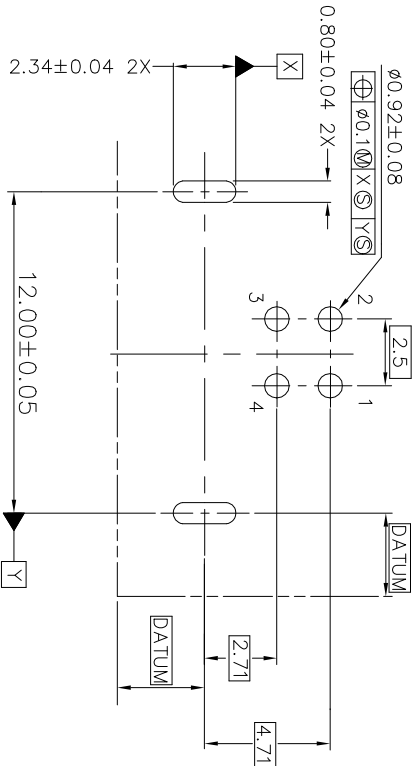




P.C. BOARD LAYOUT

STYLE 1 APPLY FOR TYPE 1 & 2



P.C. BOARD LAYOUT

STYLE 2 APPLY FOR TYPE 3

NOTES:

1. MATERIAL:

SHIELD & CONTACTS: COPPER ALLOY
HOUSING: UL 94V-0 ,HIGH TEMPERATURE THERMOPLASTIC.
COLOR: SEE PRODUCT NUMBER CODE.

2. PLATING: SEE PRODUCT NUMBER CODE.

SHIELD: BRIGHT TIN, NICKEL UNDERPLATE(USED FOR WAVE SOLDER PROCESS),
PLATING NICKEL ONLY(USED FOR PIP PROCESS).

3. DATUMS & BASIC DIMENSIONS TO BE DETERMINED BY CUSTOMER

4. RECOMMENDED BOARD THICKNESS IS 1.57 mm (.062)

5. PACKING STANDARD GS-14-920 WILL BE APPLIED FOR LEAD FREE P/N'S

6. FOR LEAD FREE P/N, THE PRODUCT MEET EUROPEAN UNION DIRECTIVES AND
OTHER COUNTRY REGULATION AS DESCRIBED IN GS-22-008

7. FOR LEAD FREE P/N'S, THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C
PEAK TEMPERATURE FOR 10 SECONDS IN A CONVECTION, INFRO-RED OR VAPOR
PHASE REFLOW OVEN.

8. THE PART CAN BE USED FOR PIP PROCESS.

mat'l. code				surface			tolerance			projection		product family	
ltr	ecn	no	dr	date	ISO 1302	ISO 406	ISO	1104	1104	1104	1104	HPL	511 USB2.0
Y					tolerances unless otherwise specified				0.0±0.30	0.00±0.20	0.000±0.10	USB RECEPTACLE B TYPE	
					angles	linear	mm	mm	mm	mm	mm		
					0±2°	0.000±0.10	scale 1:1						
					dr	Lawrence,Zang	02/26/19					dwg no	sheet2 of 2
					eng	Lawrence,Zang	02/26/19					61729	A3
					chr	Tim.Yao	02/26/19						
					qppd	Tim.Yao	02/26/19						
sheet	revision											type	Product Customer Drawing
index	sheet												